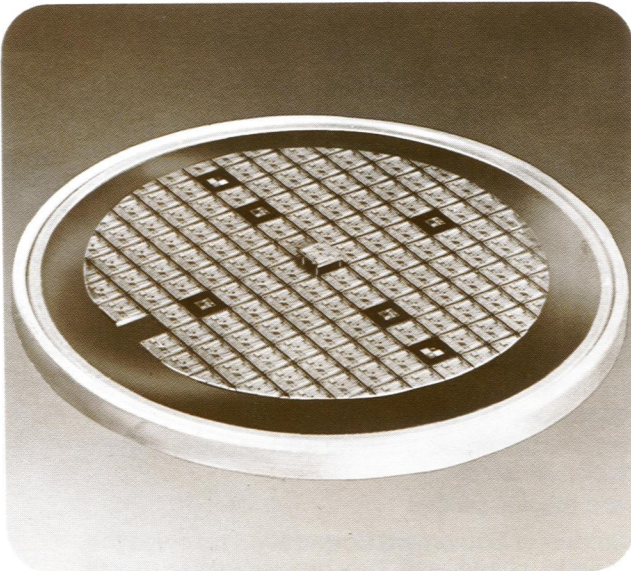


Speed Up Die Handling

MODEL 4750 DIE EJECTOR SYSTEM (POKER PLATE)

- Adaptable to Most Die Handling & Die Bonding Systems
- Virtually Maintenance Free
- One Moving Part
- Stand Alone Die Plating System



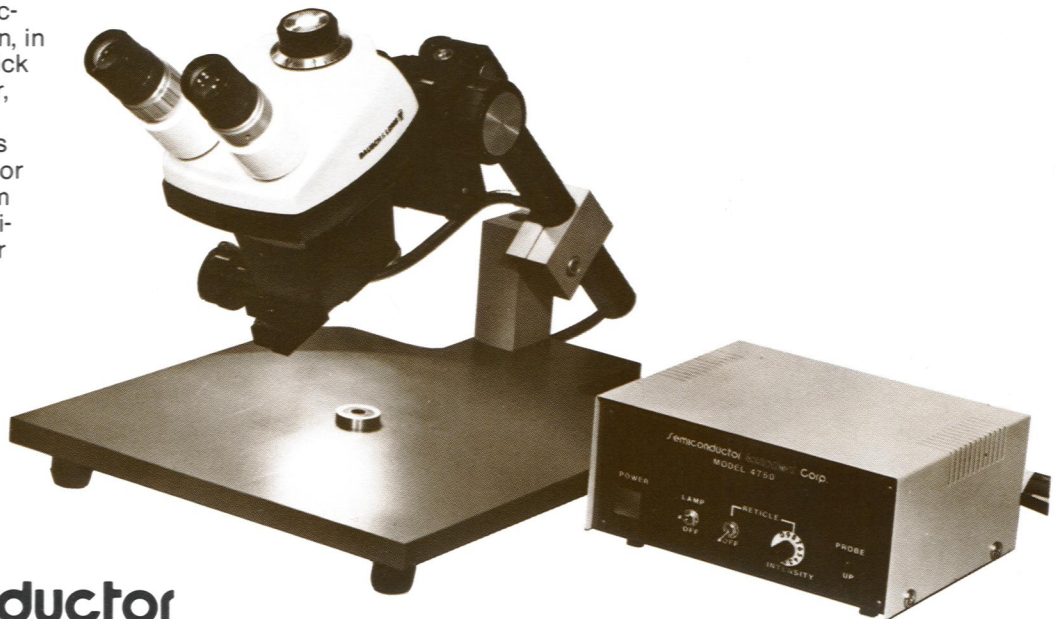
HIGH SPEED DIE HANDLING

The Model 4750 poker plate system solves the problem of quick and easy die removal from wafer mounting tape. It can be supplied as a stand alone unit or can be interfaced into your regular or high speed die bonding, pick and place, or die inspection equipment.

In operation as a stand alone unit, the operator aligns the desired die over the poker pin and presses the foot pedal. The vacuum locks the carrier in position and the poker lifts the die from the wafer mounting tape for easy removal with a vacuum pencil. In operation, in conjunction with your pick and place or die bonder, the operator aligns the desired die to the cross hair in the microscope or viewscreen, the vacuum locks the carrier in position and then the poker

lifts the die from the wafer mounting tape for pickup by your die bonding arm. The operator continues to align the cross hair to the next die.

The Model 4750 is adaptable to almost all die carrier ring or die carrier plate systems in use today or Semiconductor Equipment Corporation can supply ring sets compatible with your system. When interfaced to Semiconductor Equipment Corporation's Model 4500/4600 High Speed Die Bonders, the Model 4750 will present die to the pickup tool at rates compatible with the die bonder.



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